Compliant with IEC 62474/ D9.00

Compliant to IEC 61249-2-21:2003

MICROCHIP

Device Type: B7X PLCC-84-29.3x29.3x4.4mm-MatteTin

Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm
Silicon	7440-21-3	Die	0.304	22.000	3,036
Copper	7440-50-8	LeadFrame	17.273	1251.627	172,725
Zirconium	7440-67-7	LeadFrame	0.017	1.253	173
Silver	7440-22-4	LeadFrame	0.035	2.560	353
Resin	Trade Secret	Die Attach	0.003	0.239	33
Ag	7440-22-4	Die Attach	0.033	2.394	330
Mixed compounds	Trade Secret	Die Attach	0.001	0.103	14
Amine	Trade Secret	Die Attach	0.002	0.171	24
Gamma Butyrolactone	Trade Secret	Die Attach	0.002	0.171	24
Diglycidylether of bisphenol-F	Trade Secret	Die Attach	0.005	0.342	47
Gold	7440-57-5	Bonding Wire	0.034	2.430	335
Multi-aromatic resin	Trade Secret	Molding Compound	6.128	444.049	61,279
SiO2 Filler	60676-86-0	Molding Compound	70.267	5091.759	702,665
Carbon Black	1333-86-4	Molding Compound	0.409	29.603	4,085
Epoxy Cresol Novolac	Trade Secret	Molding Compound	1.634	118.413	16,341
Phenol Resin	Trade Secret	Molding Compound	3.268	236.826	32,682
Tin	7440-31-5	Lead Finish Plating	0.585	42.410	5,853
		TOTALS:	**100.00**	**7246.35**	**1,000,000**

7246.35 mg Total Mass

Package Homogeneous Materials

1255.44	**(mg) Total**	**LeadFrame**	**% of Total Weight**	**17.33**
	Copper	7440-50-8	99.7	
	Zirconium	7440-67-7	0.100	
	Silver	7440-22-4	0.20	
		Total	**100.00**	
3.42	**(mg) Total**	**Die Attach**	**% of Total Weight**	**0.05**
	Resin	Trade Secret	7.00	
	Ag	7440-22-4	70.00	
	Mixed compounds	Trade Secret	3.00	
	Amine	Trade Secret	5.00	
	Gamma Butyrolactone	Trade Secret	5.00	
	Diglycidylether of bisphenol-F	Trade Secret	10.00	
		Total	**100.00**	
22.00	**(mg) Total**	**Die**	**% of Total Weight**	**0.30**
	Silicon	7440-21-3	100.00	
		Total	**100.00**	
2.43	**Total (mg)**	**Bonding Wire**	**% of Total Weight**	**0.03**
	Gold	7440-57-5	100.00	
		Total	**100.00**	
5920.65	**(mg) Total**	**Molding Compound**	**% of Total Weight**	**81.71**
	Multi-aromatic resin	Trade Secret	7.50	
	SiO2 Filler	60676-86-0	86.00	
	Carbon Black	1333-86-4	0.50	
	Epoxy Cresol Novolac	Trade Secret	2.00	
	Phenol Resin	Trade Secret	4.00	
		Total	**100.00**	
42.41	**(mg) Total**	**Lead Finish Plating**	**% of Total Weight**	**0.59**
	Tin	7440-31-5	100.00	
7246.35		**Total**	**100.00**	100.00

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